Applicant:

9/661,899

Xiao-Chun Mu et al.

Examiner: Alonzo Chambliss

Serial No.:

09/661,899

Group Art Unit: 2827

Filed:

September 14, 2000

Docket: 884.791US1

Title:

PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN

ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE

STRUCTURES

APPLICATION FOR POST ISSUE PATENT TERM ADJUSTMENT UNDER 37 C.F.R § 1.705(b)

Mail Stop Issue Fee Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants hereby apply for an adjustment of the patent term due to examination delay as shown in the Original Letters Patent mailed March 13, 2007. The required fee of \$200.00 under 37 C.F.R. § 1.18(e) and a statement of facts in support of this application are attached.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

XIAO-CHUN MU ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

(612) 349-9592

By (

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 on this _______ day of May, 2007.

Name

05/16/2007 LUGNDIHZ 00000050

<u>PATENT</u>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Xiao-Chun Mu et al.

Examiner: Alonzo Chambliss

Serial No.:

09/661,899

Group Art Unit: 2827

Filed:

September 14, 2000

Docket: 884.791US1

Title:

PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN

ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE

STRUCTURES

STATEMENT OF FACTS UNDER 37 C.F.R. § 1.705(b)(2) IN SUPPORT OF APPLICATION FOR POST ISSUE PATENT TERM ADJUSTMENT

Mail Stop Issue Fee Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

The following is a statement of facts in support of the application for post issue patent term adjustment.

Applicants have calculated the correct post issue patent term adjustment as <u>599 days</u>, which was calculated as follows:

The Notice of Allowance was mailed on May 23, 2006. The Tuesday that is 28 weeks after the mailing date of the Notice of Allowance is December 26, 2006. The issue date of the patent is March 13, 2007. The difference between these two dates is 77 days.

Applicant's Issue Fee payment was timely mailed on August 23, 2006, and was received in the USPTO on August 28, 2006. This is a debit of 5 days from the Applicant's patent term. Applicant credit of 77 days – debit of 5 days gives an additional PTA of 72 days.

The Issue Notification mailed February 21, 2007 states that the Patent Term Adjustment is 527 days. This figure does not take into account the additional 72 days to which Applicant is entitled due to USPTO delay after payment of the issue fee, as detailed above. Therefore, Applicant believes that the total PTA to which Applicant is entitled is <u>599 days</u>.

The patent issuing on this application IS NOT subject to a terminal disclaimer.

Applicant has detailed above any circumstances during the prosecution of the present application that may constitute a failure to engage in reasonable efforts to conclude processing or examination of the application as set forth in 37 C.F.R. § 1.704.

Dkt: 884.791US1

Serial Number: 09/661,899

Filing Date: September 14, 2000

Title: PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE

STRUCTURES

As set forth above, Applicants' patent term adjustment should be <u>599 days</u>, and Applicants respectfully request notification to that effect. The Commissioner is invited to contact Applicants' attorney at (612) 349-9592 with any questions concerning this submission.

Respectfully submitted,

XIAO-CHUN MU ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9592

Date May 14, 2007

Ann M. McCracki

Reg. No. 42,858

Name

Signature